



Layer	Stack up	Description	Type	Base Thickness	Processed Thickness	εr	
1		PSR-4000BN (semi gloss)	soldermask		0.800	4.500	
		1/2 oz copper foil	foil	0.600	1.600		
		370HR 2116 pre-preg	pre-preg	4.830	4.710	4.020	
		370HR 2116 pre-preg	pre-preg	4.830	4.710	4.020	
				0.600	0.600		
		370HR .014 H/H core	core	14.000	14.000	4.340	
2				0.600	0.600		
		370HR 2116 pre-preg	pre-preg	4.830	4.470	4.020	
		370HR 2116 pre-preg	pre-preg	4.830	4.470	4.020	
				0.600	0.600		
		370HR .014 H/H core	core	14.000	14.000	4.340	
				0.600	0.600		
3		370HR 2116 pre-preg	pre-preg	4.830	4.710	4.020	
		370HR 2116 pre-preg	pre-preg	4.830	4.710	4.020	
				0.600	0.600		
		370HR .014 H/H core	core	14.000	14.000	4.340	
			0.600	0.600			
	370HR 2116 pre-preg	pre-preg	4.830	4.710	4.020		
4	370HR 2116 pre-preg	pre-preg	4.830	4.710	4.020		
	1/2 oz copper foil	foil	0.600	1.600			
	PSR-4000BN (semi gloss)	soldermask		0.800	4.500		

Copper Thickness = 5.600 | Dielectric Thickness = 55.780 | Solder Mask Thickness = 1.600 | Stack Up Thickness = 61.380 | Stack Up Thickness with Soldermask = 62.980 | Stack Up Cost = 20.00 |

Structure Image	Impedance ID	Structure Name	Impedance Signal Layer	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Lower Trace Width (W1)	Upper Trace Width (W2)	Ground Strip Separation (D1)	Trace Separation (S1)	Calculated Impedance	Target Impedance	Trace Thickness (T1)	Coating Above Trace (C2)	Coating Above Substrate (C1)	Coating Dielectric (CEr)
	1	Edge Coupled Coated Microstrip 1B	1	2	0	10.250	9.750	0.000	8.000	100.400	100.000	1.600	0.400	0.800	4.500
	2	Diff Coated Coplanar Strips With Lower Ground 1B	1	2	0	9.500	9.000	8.000	8.000	99.740	100.000	1.600	0.400	0.800	4.500

Drill Image	1st Layer	2nd Layer	Drill Type	Fill Type	Minimum Size
	1	6	Mechanical PTH	None	6.000

Notes

StackName: Master	Version:	Revision:	Modification:	Date of Revision:	Editor	Page 1/1
Date: 1/11/2018	Associated Documents:					
Author:						
Department:						
Site:						